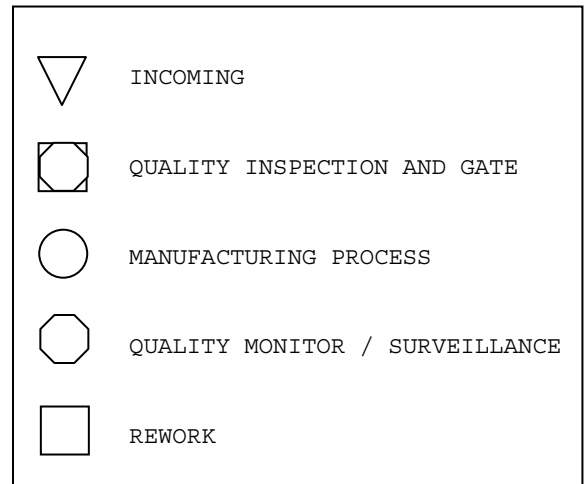


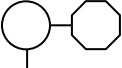



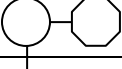

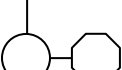
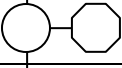
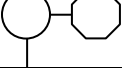





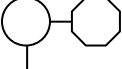

**WAFER FABRICATION FLOWCHART  
(04/06/09)**

Vendor: Linear Technology Corporation  
 Product: BICMOS Products  
 Package: All Package Types  
 Location of Wafer Fab: Linear Technology Corp., Milpitas, CA./ Camas, WA  
 Assembly: Linear Technology Corporation, Penang, Malaysia or approved assembly subcontractor  
 Final Test: Linear Technology Corp., Milpitas, CA., Singapore  
 Q.C. Test: Linear Technology Corp., Milpitas, CA., Singapore  
 Source Accept Test: Linear Technology Corp., Milpitas, CA., Singapore  
 Quality Contact: Naib Girn, LTC Milpitas, CA (408) 432-1900 Ext. 2519







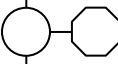

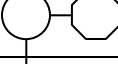

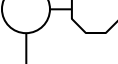
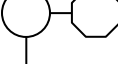
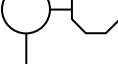
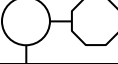
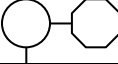
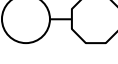
FLOW CHART	PROCESS STEP	DESCRIPTION	INSPECTION/TEST CRITERIA	METHOD & EQUIPMENT	SAMPLING PLAN	SPC TECHNIQUE
	INCOMING RAW MATERIAL INSPECTION	WAFERS	VISUAL: SCRATCHES, PITS, HAZE, CRATERS, DIMPLES, CONTAMINATION OXYGEN/CARBON MEASUREMENT RESISTIVITY / CONDUCTIVITY DIMENSIONAL THICKNESS AND TAPER/BOW ORIENTATION C OF C VERIFICATION AGAINST "MPS" REQUIREMENTS	1 X INSPECTION  INFRARED SPECTROMETER MAGNETRON V/I METER CALIPERS DIAL THICKNESS GAGE BREAK TEST	1.0% AQL TO 2.5 AQL LEVEL 1  S/S=2, ACC = 0 S/S=2, ACC = 0 2.5% AQL, LEVEL 1 2.5% AQL, LEVEL 1 S/S=1, ACC = 0 EACH BATCH	LOGBOOK
		RETICLE	C OF C VERIFICATION		EACH PLATE	
		CHEMICALS	C OF C VERIFICATION AGAINST "MPS" REQUIREMENTS			
		GASES	C OF C VERIFICATION AGAINST "MPS" REQUIREMENTS			
		TARGETS	C OF C VERIFICATION			
	INITIAL OXIDATION	FURNACE	VISUAL  OXIDE THICKNESS	UV LAMP MICROSCOPE INSPECTION  NANOSPEC	2 WAFERS/RUN < 25 DEFECTS PER WAFER  3 WAFERS / CYCLE	LOGBOOK  TREND CHART
		N-BURIED LAYER MASK	RESIST MASK	DEVELOP INSPECT	UV and MICROSCOPE	5 WAFERS 5 SPOTS AT 100X
	N-BURIED LAYER IMPLANT	IMPLANT	DOSE CHECK	THEMAWAVE	2 WAFERS/LOT	TREND CHART
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG

FLOW CHART	PROCESS STEP	DESCRIPTION	INSPECTION/TEST CRITERIA	METHOD & EQUIPMENT	SAMPLING PLAN	SPC TECHNIQUE
	N-BURIED LAYER DRIVE	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
			OXIDE THICKNESS	NANOSPEC	3 WAFERS/CYCLE	
	P-BURIED LAYER MASK	RESIST MASK	DEVELOP INSPECT	UV and MICROSCOPE	5 WAFERS 5 SPOTS AT 100X	PRODUCTION LOG
	P-BURIED LAYER IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	P-BURIED LAYER DRIVE	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
			OXIDE THICKNESS	NANOSPEC	3 WAFERS/CYCLE	
	EPI	DEPOSIT EPI ASM	VISUAL	UV LAMP	INSPECT 2 WAFERS / RUN	X Bar & MOVING R
				INTERFERENCE CONTRAST MICROSCOPE		
			Rs EPI THICKNESS	4 POINT PROBE	2 READING/PASS	
				FTIR	1 WAFER/LOT	LOGBOOK
	PAD OXIDATION	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
			OXIDE THICKNESS	NANOSPEC	3 WAFERS/CYCLE	TREND CHART
	HV P-WELL MASK	RESIST MASK/ HF ETCH BATH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	HV P-WELL IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	P+ ISOLATION MASK	RESIST MASK/ HF ETCH BATH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	P+ ISOLATION IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	N+ SINKER MASK	RESIST MASK/ HF ETCH BATH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	N+ SINKER IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	LOGBOOK
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG

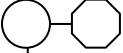

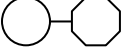
FLOW CHART	PROCESS STEP	DESCRIPTION	INSPECTION/TEST CRITERIA	METHOD & EQUIPMENT	SAMPLING PLAN	SPC TECHNIQUE
	N-WELL MASK	RESIST MASK	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	LV N-WELL IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	P-WELL MASK	RESIST MASK	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	LV P-WELL IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	NITRIDE DEPOSITION	LPCVD NITRIDE DEPOSITION	VISUAL	UV LAMP	100%, MORE THAN 2 COLOR CHANGE IS FAIL	TREND CHART
				10X MICROSCOPE	2 WAFERS/CYCLE <5 DEFECTS/PER FIELD OF VIEW	
			NITRIDE THICKNESS	NANOSPEC	3 WAFERS/CYCLE	
	WELL/SINKER DRIVE	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
	ACTIVE MASK	RESIST MASK PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	P FIELD IMPLANT MASK	RESIST MASK	VISUAL INSPECTION	MICROSCOPE 400X	"S" PATTERN SCAN OF THE WAFERS	PRODUCTION LOG
	BORON FIELD IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS / LOT	TREND CHART
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	LOCOS OXIDE	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK TREND CHART
			OXIDE THICKNESS	NANOSPEC	3 WAFERS/CYCLE	
	STRIP NITRIDE	H3PO4 ETCH BATH	VISUAL	UV LAMP MICROSCOPE INSPECTION		LOGBOOK
			THICKNESS	NANOSPEC	2 WAFERS /LOT	
	SACRIFICIAL OXIDATION	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
			OXIDE THICKNESS	NANOSPEC	3 WAFERS / CYCLE	
	STRIP OXIDE	HF ETCH BATH	VISUAL	UV LAMP MICROSCOPE INSPECTION		LOGBOOK
			THICKNESS	NANOSPEC	2 WAFERS /LOT	

FLOW CHART	PROCESS STEP	DESCRIPTION	INSPECTION/TEST CRITERIA	METHOD & EQUIPMENT	SAMPLING PLAN	SPC TECHNIQUE
○	THICK GATE OXIDE	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
			OXIDE THICKNESS	NANOSPEC	3 WAFERS/CYCLE	TREND CHART
○	THIN OXIDE MASK	RESIST MASK/ HF ETCH BATH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
○	THIN GATE OXIDE	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
			OXIDE THICKNESS	ELLIPSOMETER	3 WAFERS/CYCLE	TREND CHART
○	POLY 1 DEPOSITION	LPCVD DEPOSITION	VISUAL	UV LAMP	100%, MORE THAN 2 COLOR CHANGE IS FAIL	TREND CHART
				10X MICROSCOPE	3 WAFERS/CYCLE <5 DEFECTS/PER FIELD OF VIEW	
			POLY THICKNESS	NANOSPEC	3 WAFERS/CYCLE	
○	VT MASK	RESIST MASK	DEVELOP INSPECT	UV and MICROSCOPE	5 WAFERS 5 SPOTS AT 100X	PRODUCTION LOG
○	LT THRESHOLD ADJUST IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
○	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
○	VTHV IMPLANT MASK	RESIST MASK	DEVELOP INSPECT	UV and MICROSCOPE	5 WAFERS 5 SPOTS AT 100X	PRODUCTION LOG
○	HV THRESHOLD ADJUST IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
○	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
○	WSIX	CVD	REFLECTIVITY	NANOSPEC	1 WF PER BATCH LOT	TREND CHART
				10X MICROSCOPE	2 WAFERS/RUN <5 DEFECTS PER FIELD OF VIEW	
			Rs	Four Point Probe	1 WF PER BATCH LOT	
○	POLY 1 MASK	RESIST MASK PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X AND 1000X	PRODUCTION LOG
			CRITICAL DIMENSION	SEM	1 WAFER (5 SPOTS)	X BAR & R
○	NPN BASE MASK	RESIST MASK	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
○	NPN BASE IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
○	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG

FLOW CHART	PROCESS STEP	DESCRIPTION	INSPECTION/TEST CRITERIA	METHOD & EQUIPMENT	SAMPLING PLAN	SPC TECHNIQUE
	CAP OXIDE DEPOSITION	OXIDE DEPOSITION	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK X-BAR & R
			THICKNESS	ELLIPSOMETER	3 WAFERS/CYCLE	
	POLY 2 DEPOSITION	LPCVD DEPOSITION	VISUAL	UV LAMP	100%, MORE THAN 2 COLOR CHANGE IS FAIL	TREND CHART
				10X MICROSCOPE	2 WAFERS/CYCLE <5 DEFECTS/PER FIELD OF VIEW	
			THICKNESS	NANOSPEC	3 WAFERS/CYCLE	
	POLY 2 MASK	RESIST MASK PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	WSIX ANNEAL	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
	PLDD MASK	RESIST MASK	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	PLDD IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	NLDD MASK	RESIST MASK	DEVELOP INSPECT	UV and MICROSCOPE	5 WAFERS 5 SPOTS AT 100X	PRODUCTION LOG
	ANTI PUNCH THROUGH IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
	NLDD IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	SPACER DEPOSITION	OXIDE DEPOSITION	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	NANOSPEC	1 WAFER/CYCLE	
	SPACER ANNEAL	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
	SPACER ETCH	PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
			OXIDE MEASUREMENT	NANOSPEC	2 WAFER (3 SPOTS)	X BAR & R
	P+ S/D MASK	RESIST MASK	DEVELOP INSPECT	UV and MICROSCOPE	5 WAFERS 5 SPOTS AT 100X	PRODUCTION LOG
	P+ S/D IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
			VISUAL	MICROSCOPE	2 WAFERS/LOT	

FLOW CHART	PROCESS STEP	DESCRIPTION	INSPECTION/TEST CRITERIA	METHOD & EQUIPMENT	SAMPLING PLAN	SPC TECHNIQUE
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	N+ S/D IMPLANT MASK	RESIST MASK	DEVELOP INSPECT	UV and MICROSCOPE	5 WAFERS 5 SPOTS AT 100X	PRODUCTION LOG
	N+ S/D IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
			VISUAL	MICROSCOPE	2 WAFERS/LOT	
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	THIN OX DEPOSITION	OXIDE DEPOSITION	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	NANOSPEC	1 WAFER/CYCLE	
	S/D ANNEAL	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
	BPSG DEPOSITION	OXIDE DEPOSITION	VISUAL	UV LAMP	3 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	NANOSPEC	3 WAFERS/CYCLE	
			WT% B WT% P	BIORAD	WEEKLY	
	ANNEAL	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
	THIN FILM DEPOSITION	PVD SPUTTER		10X MICROSCOPE	2 WAFERS/RUN <5 DEFECTS PER FIELD OF VIEW	TREND CHART
			Rs	FOUR POINT PROBE	1 WAFERS/LOT	
	THIN FILM RESISTOR MASK	RESIST MASK PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X AND 500X	PRODUCTION LOG
			VISUAL INSPECTION	MICROSCOPE 100X	"S" PATTERN SCAN OF THE WAFERS	
	SI-RICH OXIDE	OXIDE DEPOSITION	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	NANOSPEC	1 WAFER/CYCLE	
	CONTACT MASK	RESIST MASK PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	THIN FILM CONTACT MASK	RESIST MASK HF ETCHANT BATH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	TIN BARRIER	PVD SPUTTER	VISUAL	10X MICROSCOPE	2 WAFERS/RUN <5 DEFECTS PER FIELD OF VIEW	TREND CHART
			Rs	FOUR POINT PROBE	1 WAFERS/LOT	

FLOW CHART	PROCESS STEP	DESCRIPTION	INSPECTION/TEST CRITERIA	METHOD & EQUIPMENT	SAMPLING PLAN	SPC TECHNIQUE
	BARRIER ANNEAL	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
	METAL-1 DEPOSITION	PVD SPUTTER	VISUAL	UV LAMP	2 WAFERS/RUN	LOGBOOK
				10X MICROSCOPE	2 WAFERS/RUN <5 DEFECTS PER FIELD OF VIEW	
			Rs	FOUR POINT PROBE	1 WAFERS/LOT	TREND CHART
	METAL MASK	RESIST MASK PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X AND 1000X	PRODUCTION LOG
	ILD 1	OXIDE DEPOSITION	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN	LOGBOOK
			THICKNESS	NANOSPEC	1 WAFER/CYCLE	TREND CHART
			STRESS	STRESS GAGE	1 WAFER/CYCLE	
	SOG	SPIN-ON-GLASS	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	NANOSPEC	1 WAFER/CYCLE	
	SOG ANNEAL	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
	SOG ETCHBACK	PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
			OXIDE MEASUREMENT	NANOSPEC	2 WAFER (3 SPOTS)	X BAR & R
	ILD 2	OXIDE DEPOSITION	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN	LOGBOOK
			THICKNESS	NANOSPEC	1 WAFER/CYCLE	TREND CHART
			STRESS	STRESS GAGE	1 WAFER/CYCLE	
	VIA MASK	RESIST MASK PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X AND 1000X	PRODUCTION LOG
	METAL-2 DEPOSITION	PVD SPUTTER	VISUAL	UV LAMP	2 WAFERS/RUN	LOGBOOK
				10X MICROSCOPE	2 WAFERS/RUN <5 DEFECTS PER FIELD OF VIEW	
				Rs	FOUR POINT PROBE	1 WAFERS/LOT
	METAL MASK	RESIST MASK PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X AND 1000X	PRODUCTION LOG
	PASSIVATION DEPOSITION	OXIDE / PEN DEPOSITION	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	NANOSPEC	1 WAFER/CYCLE	
			INDEX OF REFRACTION	ELLIPSOMETER	1 WAFER/WEEK	

FLOW CHART	PROCESS STEP	DESCRIPTION	INSPECTION/TEST CRITERIA	METHOD & EQUIPMENT	SAMPLING PLAN	SPC TECHNIQUE
	PAD MASK	RESIST MASK PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	ALLOY	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
	ELECTRICAL TEST	EVALUATE ELECTRICAL PARAMETERS			100%	LOGBOOK